

AMENDMENT

U.S. Patent Application Serial No. 09/805,559

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facilitate deformation of the pad when the bumps are pressed against the pads and to form a space in which the insulating adhesive is filled, and wherein
contraction of the insulating adhesive maintains joints of the bumps and the pads, said joints being made by deformation of the pads.

11. (Amended) A structure according to claim 8, wherein
a member between said semiconductor device and said head is provided, said member having a thermal characteristic of delaying transmission of heat, and
a heat treated at a temperature at which said insulating adhesive is hardened presses said semiconductor device on said board so that each of said bumps is pressed on a corresponding one of said pads, wherein pressure of said bumps against said pads reaches a predetermined value which plastically deforms said pads before a temperature of said insulating adhesive to which heat is supplied from said head reaches temperature at which said insulating adhesive is hardened.
